



## Material Content Data Sheet



<b>Sales Product Name</b>				IPU60R950C6		<b>Issued</b>		8. October 2014	
<b>MA#</b>				MA000986850					
<b>Package</b>				PG-TO251-3-341		<b>Weight*</b>		381.53 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.144	0.56	0.56	5619	5619	
leadframe	non noble metal	iron	7439-89-6	0.229	0.06		601		
	inorganic material	phosphorus	7723-14-0	0.069	0.02		180		
	non noble metal	copper	7440-50-8	228.946	60.02	60.10	600083	600864	
wire	non noble metal	aluminium	7429-90-5	0.432	0.11	0.11	1132	1132	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.736	0.46		4550		
	plastics	brominated resin	-	1.860	0.49		4875		
	organic material	carbon black	1333-86-4	1.984	0.52		5201		
	plastics	epoxy resin	-	16.741	4.39		43879		
	inorganic material	silicondioxide	60676-86-0	101.687	26.65	32.51	266527	325032	
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9803	9803	
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1334	1334	
solder	noble metal	silver	7440-22-4	0.056	0.01		147		
	non noble metal	tin	7440-31-5	0.045	0.01		118		
	non noble metal	lead	7439-92-1	2.144	0.56	0.58	5621	5886	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.00		50		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	copper	7440-50-8	19.177	5.03	5.03	50265	50330	
*deviation	< 10%					Sum in total:	100.00	1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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